ROGERS CORPORATION

\\\ Datasheet

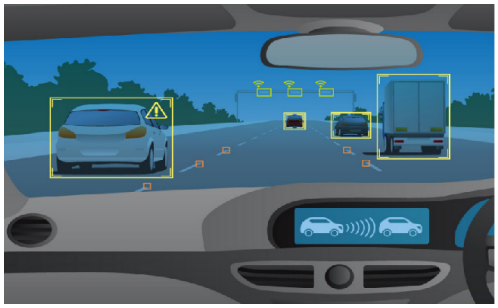
RO3000® Series Circuit Materials

RO3003™, RO3006™, RO3010™ and RO3035™ High Frequency Laminates

RO3000® high frequency circuit materials are ceramic-filled PTFE composites intended for use in commercial microwave and RF applications. This family of products was designed to offer exceptional electrical and mechanical stability at competitive prices. RO3000 series laminates are ceramic-filled PTFE based circuit materials with mechanical properties that are consistent regardless of the dielectric constant selected. This allows the designer to develop multilayer board designs that use different dielectric constant materials for individual layers, without encountering warpage or reliability problems.

RO3000 materials exhibit a coefficient of thermal expansion (CTE) in the X and Y axis of 17 ppm/°C. This expansion coefficient is matched to that of copper, which allows thematerial to exhibit excellent dimensional stability, with typical etch shrinkage (after etch and bake) of less than 0.5 mils per inch. The Z-axis CTE is 24 ppm/ °C, which providesexceptional plated through-hole reliability, even in severe thermal environments. The dielectric constant versus temperature for RO3003™ and RO3035™ materials is very stable (Chart 1).

RO3000 series laminates can be fabricated into printed circuit boards using standard PTFE circuit board processing techniques, with minor modifications as described in the application note "Fabrication Guidelines for RO3000 Series High Frequency Circuit Materials."



\\\ Features and Benefits:

Low dielectric loss (RO3003™ laminates)

- Laminates can be used in applictions up to 77 GHz.

Excellent mechanical properties versus temperature

- Reliable stripline and multilayer board constructions.

Uniform mechanical properties for a range of dielectric constants

- Ideal for multilayer board designs with a range of dielectric constants
- Suitable for use with epoxy glass multilayer board hybrid designs

Stable dielectric constant versustemperature and frequency (RO3003 laminates)

- Ideal for band pass filters, microstrip patch antennas, and voltage controlled oscillators.

Low in-plane expansion coefficient (match to copper)

- Allows for more reliable surface mounted assemblies
- Ideal for applications sensitive to temperature change
- Excellent dimensional stability

Volume manufacturing process

- Economical laminate pricing

\\\ Typical Applications:

- Automotive radar applications
- Global positioning satellite antennas
- Cellular telecommunications systems -power amplifiers and antennas
- Patch antenna for wireless communications
- Direct broadcast satellites
- Datalink on cable systems
- Remote meter readers
- Power backplanes

\\\ Standard Properties Table

Properties	Typical Value				Units	Test Conditions		Test Method
	RO3003	RO3035	RO3006	RO3010				
Electrical Properties								
Dielectric Constant (process)	3.00± 0.04	3.50 ± 0.05	6.15 ± 0.15	10.2 ± 0.30	-	23˚C	10 GHz	IPC TM-650 2.5.5.5
Dielectric Constant (design)	3.00	3.60	6.50	11.20	-	8 GHz - 40 GHz		Differential Phase Length
Dissapation Factor	0.0010	0.0015	0.0020	0.0022	-	23˚C	10 GHz	IPC TM-650 2.5.5.5
Thermal Coefficient of Dielectric Constant	-3	-45	-262	-395	ppm/˚C	-50 to 150˚C	10 GHz	IPC TM-650 2.5.5.5
Volume Resistivity	10^7	10^7	10^5	10^5	MΩ-cm	Condition A		IPC TM-650 2.5.17.1
Surface Resistivity	10^7	10^7	10^5	10^5	MΩ	Condition A		IPC TM-650 2.5.17.1
Thermal Properties								
Decomposition Temperature (Td)	500	500	500	500	˚C TGA	-		ASTM D3850
Coefficient of Thermal Expansion - x	17	17	17	13	ppm/˚C	-55 to 288˚C 23˚C/ 50% RH		IPC TM-650 2.4.41
Coefficient of Thermal Expansion - y	16	17	17	11	ppm/˚C			
Coefficient of Thermal Expansion - z	25	24	24	16	ppm/˚C			
Thermal Conductivity	0.50	0.50	0.79	0.95	W/(m·K)	50˚C		ASTM D5470
Mechanical Properties								
Copper Peel Strength	12.7	10.2	7.1	9.4	lbs/in	1 oz. EDC After Solder Float		IPC TM-650 2.4.8
Young's Modulus	930 823	1025 1006	1498 1293	1902 1934	MPa	23˚C		ASTM D638
Dimensional Stability (MD, CMD)	-0.06 0.07	-0.11 0.11	-0.27 -0.15	-0.35 -0.31	mm/m	Condition A		IPC TM-650 2.2.4
Physical Properties								
Flammability	V-0	V-0	V-0	V-0	-	-		UL 94
Moisture Absorption	0.04	0.04	0.02	0.05	%	D48/50		IPC TM-650 2.6.2.1
Density	2.1	2.1	2.6	2.8	g/cm^3	23˚C		ASTM D792
Specifc Heat Capacity	0.9		0.86	0.8	J/g/K	-		Calculated
Lead Free Process Compatible	Yes	Yes	Yes	Yes	-	-		-

1 Typical values are a representation of an average value for the population of the property. For specification values contact Rogers Corporation.
2 The design Dk is an average number from several different tested lots of material and on the most common thickness/s. If more detailed information is required, please contact Rogers Corporation or refer to Rogers' technical papers in the Roger Technology Support Hub available at http://www.rogerscorp.com/ techub

Property Charts

Chart 1: RO3003 and RO3035 Laminate Dielectric Constant vs. Temperature

The data in Chart 1 demonstrates the excellent stability of dielectric constant over temperature for RO3003 & RO3035 laminates, including the elimination of the step change in dielectric constant, which occurs near room temperature with PTFE glass materials.
The data in Chart 2 shows the

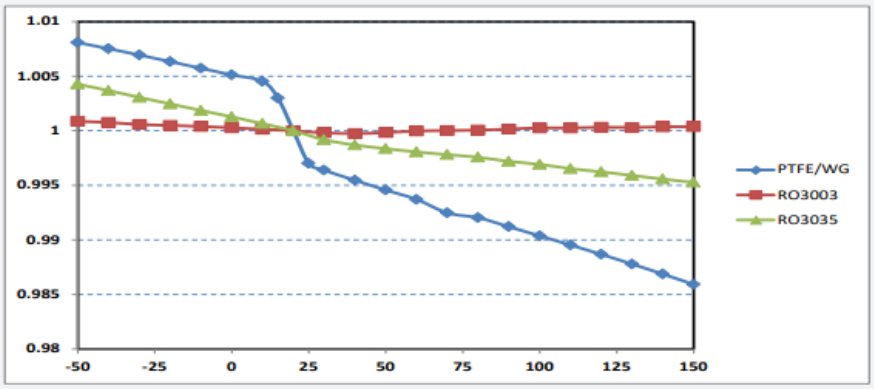


Chart 2: RO3003 and RO3035 Dissipation Factor

distribution of dissipation factor for RO3003 and RO3035 materials.

Test Method: IPC-TM-650 2.5.5.5
Condition: 10 GHz 23° C

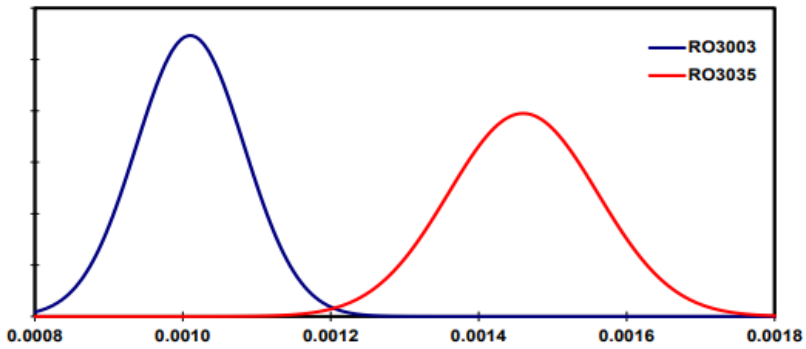
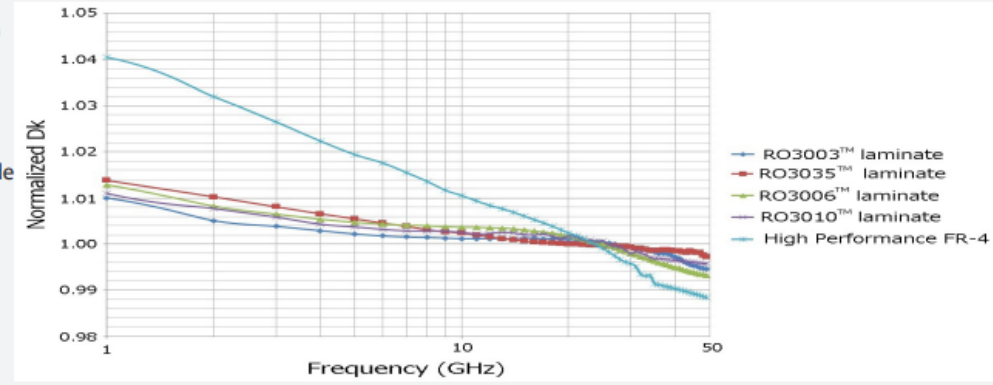


Chart 3: Normalized Dk vs. Frequency using microstrip differential phase length method 50 ohm microstrip circuits based on ~20mil thick laminates

Chart 3 demonstrates the stability of dielectric constant for RO3000 series products over frequency. This stability simplifies the design of broadband components as well as allowing the materials to be used in a wide range of applications over a very broad range of frequencies.



\\\ Available Configurations

Standard Thicknesses	Standard Panel Sizes	Standard Cladding
RO3003: 0.005" (0.13mm) +/- 0.0005" 0.010" (0.25mm) +/- 0.0007" 0.020" (0.51mm) +/- 0.0010" 0.030" (0.76mm) +/- 0.0015" 0.060" (1.52mm) +/- 0.0030" RO3006/RO3010: 0.005" (0.13mm) +/- 0.0005" 0.010" (0.25mm) +/- 0.0007" 0.025" (0.64mm) +/- 0.0010" 0.050" (1.28mm) +/- 0.0020" RO3035 0.010" (0.25mm) +/- 0.0005" 0.020" (0.51mm) +/- 0.0010" 0.060" (1.52mm) +/- 0.0030"	**RO3003/RO3006/RO3010/RO3035:** 12" X 18" (305 X 457mm) 24" X 18" (610 X 457mm) **RO3003 0.005" and 0.010":** 12" X 18" (305 X 457mm) 24" X 18" (610 X 457mm) 24" X 21" (610 X 533mm)	**RO3003:** Electrodeposited Copper Foil ½ oz. (18µm) 1 oz. (35µm) Rolled Copper Foil ½ oz. (18µm) 1 oz. (35µm) **RO3006/RO3010/RO3035:** Electrodeposited Copper Foil ½ oz. (18µm) 1 oz. (35µm)

*Contact Customer Service or Sales Engineering to inquire about other available product configurations including additional thicknesses, panel sizes and claddings.

\\\ 100 S. Roosevelt Avenue \\\ Chandler, AZ 85226 \\\ Tel: 480-961-1382 \\\ Fax: 480-961-4533 \\\ www.rogerscorp.com

Revised 1687 013024 **Publication #92-130**

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